

APPLICATION DATA SHEET**Inventor Information**

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Application Information

Title : MICROELECTRONIC SUBSTRATE ASSEMBLY
PLANARIZING MACHINES AND METHODS OF
MECHANICAL AND CHEMICAL-MECHANICAL
PLANARIZATION OF MICROELECTRONIC SUBSTRATE
ASSEMBLIES
Total Drawing Sheets : 9
Formal Drawings : YES
Application Type : Utility
Attorney Docket Number : 500571.03 (29210/US/2)
Assigned : Yes (Large Entity)

Representative Information

Representative Customer No. : 27,076



Continuity Information

This application is a	:	continuation of
>Application One	:	09/687,209
Filing Date	:	October 13, 2000
which is a	:	divisional of
>>Application Two	:	09/145,400
Filing Date	:	September 1, 1998
Patent Number	:	6,439,967

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